

4

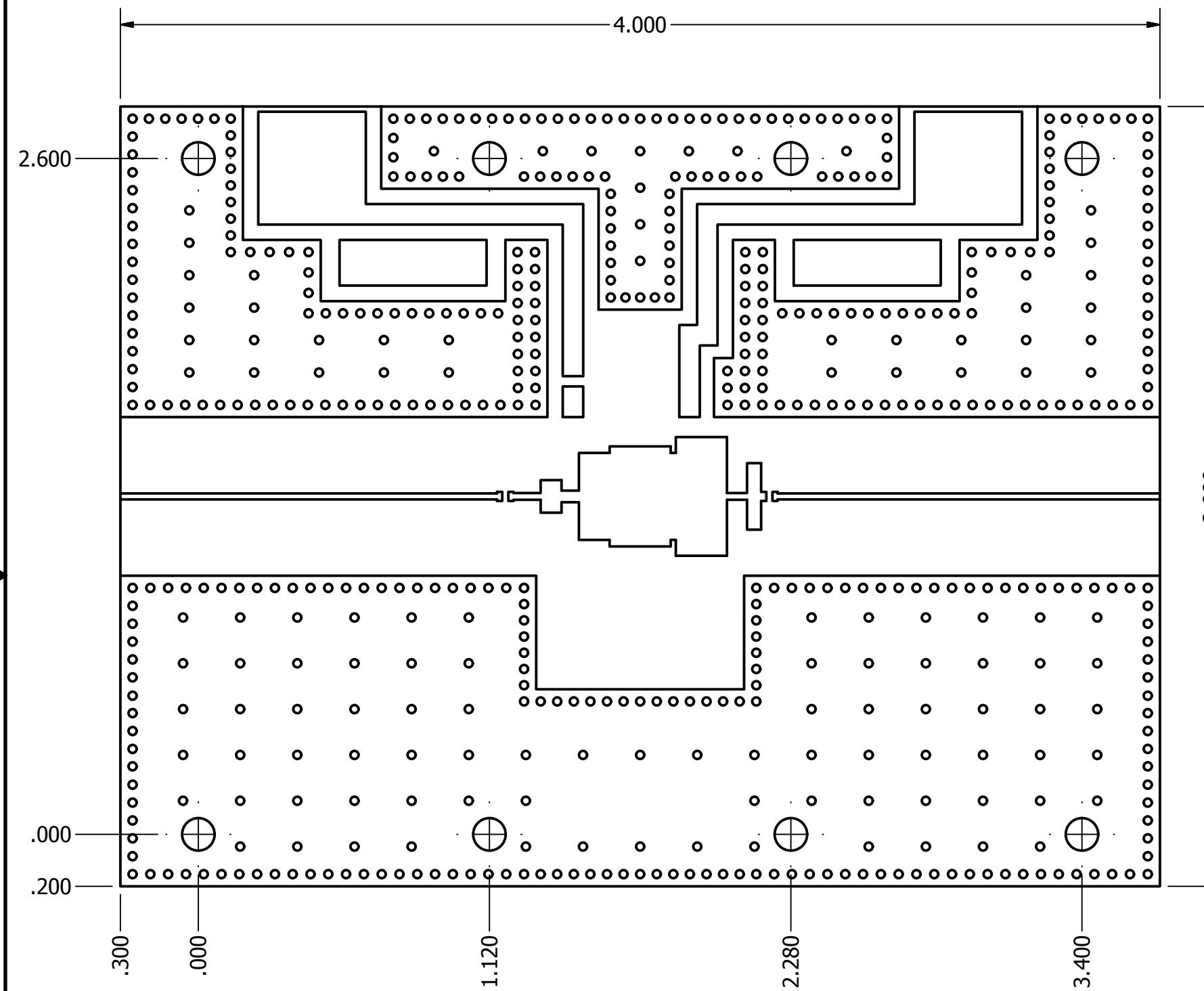
3

2

1

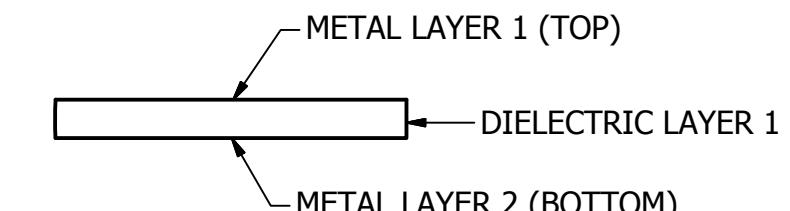
REVISION HISTORY

ECN	REV	DESCRIPTION	DATE	APPROVED
	NE	NEW RELEASE	4/19/11	I.MEDINA



A

B

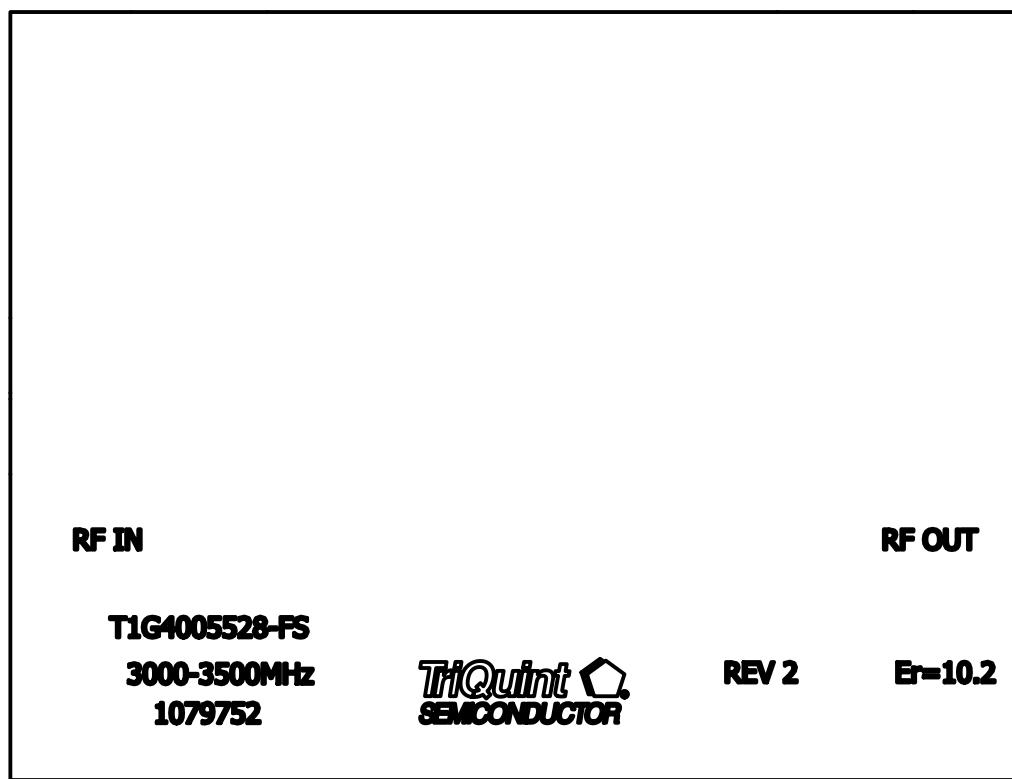
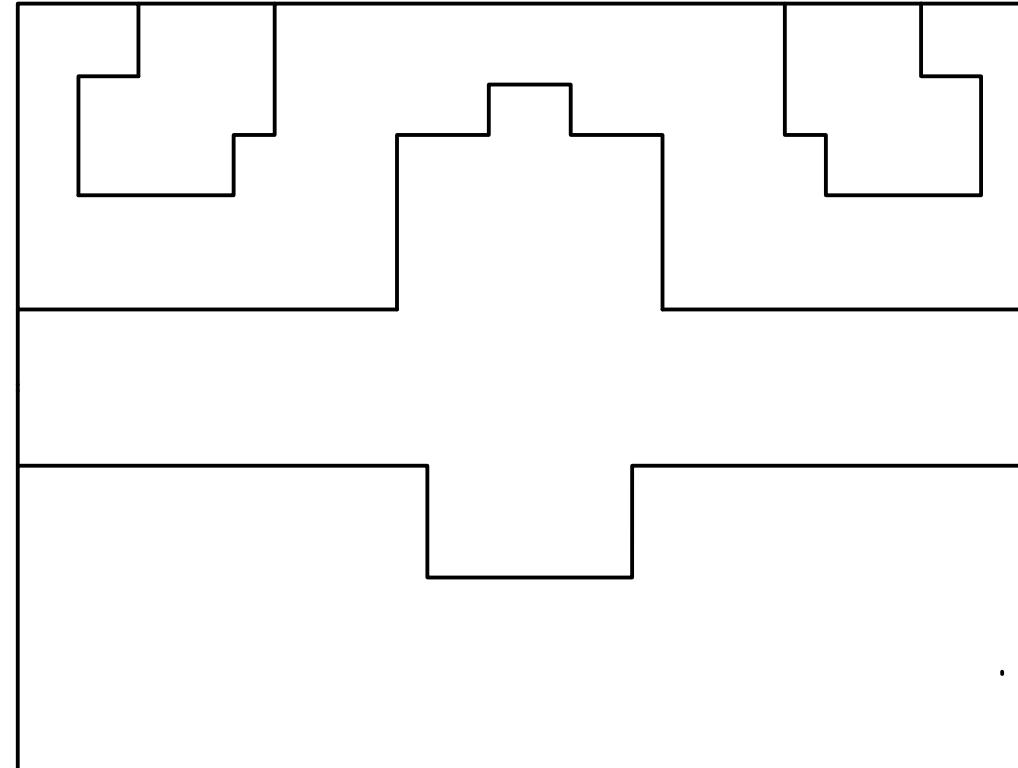
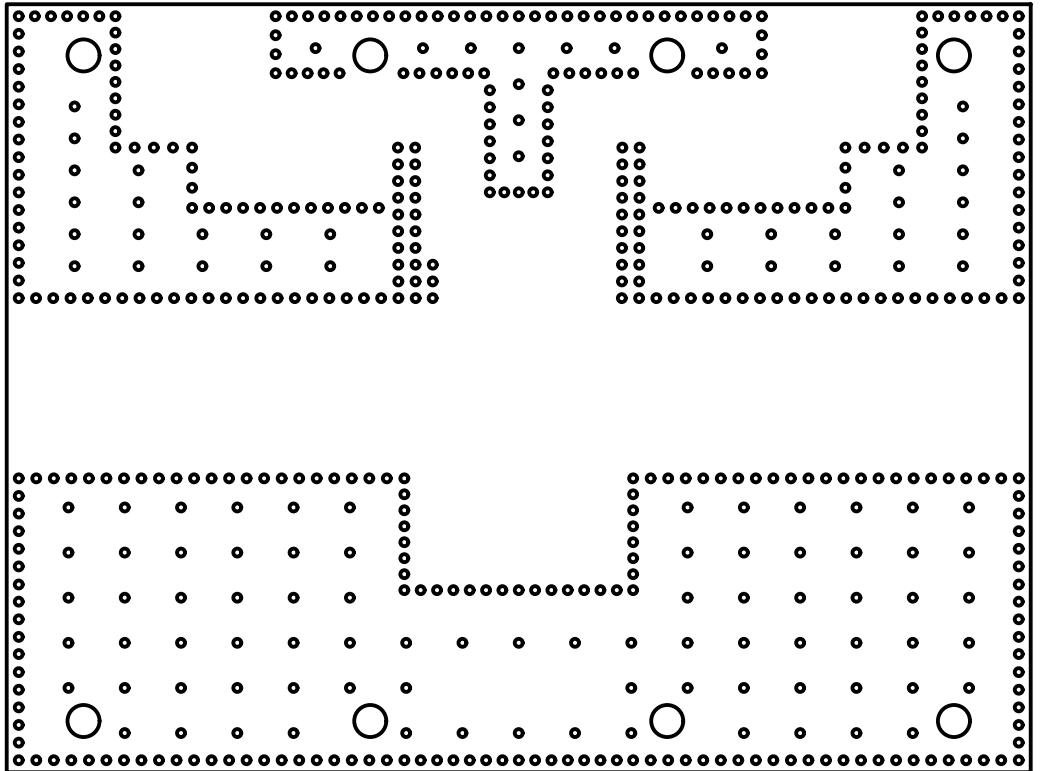


DETAIL A
SCALE 20 : 1

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL:
 - DIELECTRIC LAYER 1 - ROGERS 3210, 0.025 THICK
 - METAL LAYER 1 - 2 - 1.0 OZ. COPPER
 - SOLDERMASK - BLUE
 - SILKSCREEN - WHITE
2. SOLDERMASK IN AREAS INDICATED. 0.001 INCHES THICK MAX
3. COPPER IS PULLED BACK 0.003 ON METAL LAYER 1 (TOP), METAL LAYER 2 (BOTTOM), FROM EDGE OF PCB.
4. PLATING:
 - A. ELECTROPLATE COPPER 0.0012 INCH THICK
 - B. IMMERSION GOLD (2-6um) IAW IPC-4552 CLASS 38.
5. CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001 INCHES OF CAD DATA BASE.
6. ALL HOLES TO BE LOCATED WITHIN ± 0.0015 INCHES OF CAD DATABASE.
7. ALL BURRS SHALL BE REMOVED.
8. FABRICATE IN ACCORDANCE WITH IPC 6012A, CLASS 2 PER IPC 6011.

		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: DECIMALS ANGLES .XX±.01 ±.1' .XXX±.005 .XXXX±.0010		CONTRACT OR PRODUCT LINE		TriQuint SEMICONDUCTOR	500 W RENNER RD RICHARDSON TX 75080 TEL 972.994.8200 FAX 972.994.8504	
		DO NOT SCALE DRAWING		APPROVALS	DATE		TITLE	
		THIS DRAWING CONTAINS PROPRIETARY INFORMATION THAT MAY NOT BE USED WITHOUT THE WRITTEN CONSENT OF TRIQUINT SEMICONDUCTOR. FAILURE TO COMPLY MAY RESULT IN LEGAL ACTIONS OR CRIMINAL PROSECUTION		DRAWN IMedina	4/19/2011	T1G4005528FS EVB REV 2 BOARD		
NEXT ASSY		USED ON		CHECKED				
		APPLICATION		ENGR				
				MFG				
				QA				
SIZE	CAGE CODE	DWG NO		DP00631			REV	
B	1CVM1						NE	
SCALE	CADFILE	SHEET		AD1_DP00631.idw			1 OF 3	

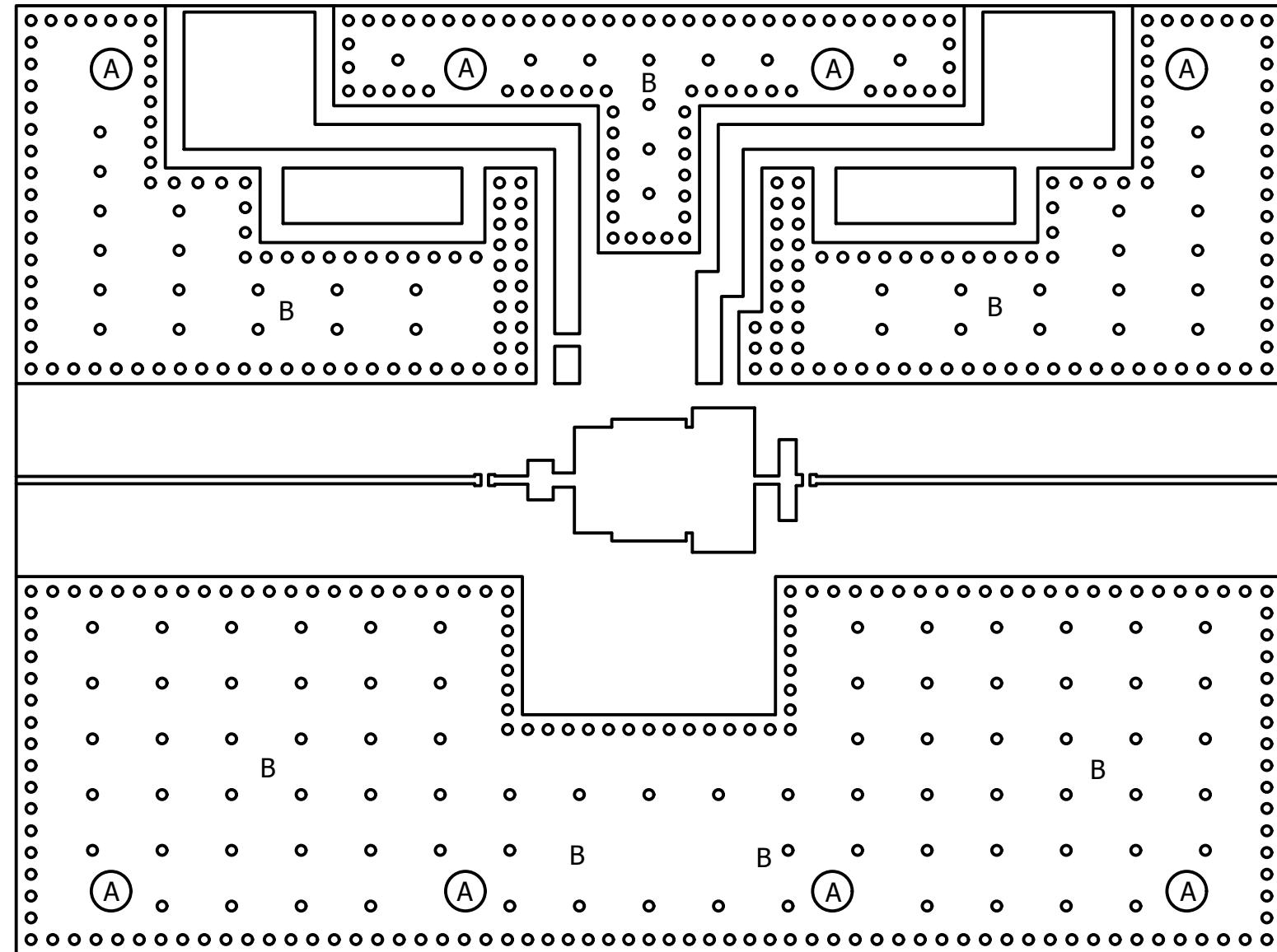


SILKSCREEN (TOP)

SIZE	CAGE CODE	DWG NO
B	1CVM1	DP00631
SCALE	CADFILE	REV NE

SCALE CADFILE SHEET 2 OF 3
AD1 DP00631.idw

4 | 3 | 2 | 1



DRILL SIZE

DRILL TABLE			
SYMBOL	QUANTITY	HOLE SIZE	DESCRIPTION
A	8	0.125	PTH
B	541	0.031	PTH

SIZE **B** CAGE CODE **1CVM1** DWG NO **DP00631** REV **NE**
SCALE CADFILE SHEET **AD1 DP00631.idw** 3 OF 3

4 | 3 | 2 | 1